

EL979953748

Inventor: Kyle K. Kirby; Shuang Meng; and Garo J. Derderian

Title: Methods of Fabricating Interconnects for Semiconductor Components

Assignee: Micron Technology, Inc.

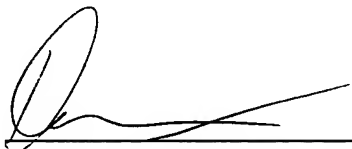
**INFORMATION DISCLOSURE STATEMENT**

References – See Attached Form PTO-1449

The attached form PTO-1449 is submitted in compliance with 37 CFR § 1.56. Copies of the cited art are included with the exception of U.S. patents and published U.S. applications (1276 OG 55). No admission is made regarding whether all the submitted references are prior art.

Respectfully submitted,

Dated: 2/20/04

By:   
David G. Latwesen, Ph.D.  
Reg. No. 38,533

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| Form PTO-1449  |  | U.S. DEPARTMENT OF COMMERCE<br>PATENT AND TRADEMARK OFFICE |  | ATTY. DOCKET NO.<br>MI22-2401        |  | SERIAL NO.<br>Filed Herewith |  |
| <b>LIST OF ART CITED BY APPLICANT</b><br>(Use several sheets if necessary) |  |  |  | APPLICANT<br>Micron Technology, Inc. |  |                              |  |
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| U.S. PATENT DOCUMENTS |    |                 |         |              |       |            |                            |
|-----------------------|----|-----------------|---------|--------------|-------|------------|----------------------------|
| *Examiner Initial     |    | Document Number | Date    | Name         | Class | Subclasses | Filing Date If Appropriate |
|                       | AA | 6,107,109       | 8/22/00 | Akram et al. |       |            |                            |
|                       | AB | 6,114,240       | 9/5/00  | Akram et al. |       |            |                            |
|                       | AC | 6,294,837       | 9/25/01 | Akram et al. |       |            |                            |
|                       | AD |                 |         |              |       |            |                            |
|                       | AE |                 |         |              |       |            |                            |
|                       | AF |                 |         |              |       |            |                            |
|                       | AG |                 |         |              |       |            |                            |
|                       | AH |                 |         |              |       |            |                            |
|                       | AI |                 |         |              |       |            |                            |
|                       | AJ |                 |         |              |       |            |                            |

| FOREIGN PATENT DOCUMENTS |    |                 |      |         |       |            |             |    |
|--------------------------|----|-----------------|------|---------|-------|------------|-------------|----|
|                          |    | Document Number | Date | Country | Class | Subclasses | Translation |    |
|                          |    |                 |      |         |       |            | Yes         | No |
|                          | AK |                 |      |         |       |            |             |    |
|                          | AL |                 |      |         |       |            |             |    |

| OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.) |    |  |   |
|---|----|--|---|
|   | AM |  | Electroless Plating; <a href="http://www.corrosion-doctors.org/MetalCoatings/Electroless.htm">http://www.corrosion-doctors.org/MetalCoatings/Electroless.htm</a> ; 12/5/2003; pp. 1-4   |
|   |    |  |   |
|   | AN |  | Electroless Plating; <a href="http://www.corrosion-doctors.org/MetalCoatings/Electroless.htm">http://www.corrosion-doctors.org/MetalCoatings/Electroless.htm</a> ; 10/20/2003; pp. 1-2  |
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|   | AO |  | Slide Show: "Through-Water Copper Electroplating for RF Silicon Technology"; N.T. Nguyen et al.; DIMES - TU Delft, Netherlands; <a href="http://www.essderc2002.deis.unibo.it/ESSDERC_web/Session_D11/D11_2.pdf">http://www.essderc2002.deis.unibo.it/ESSDERC_web/Session_D11/D11_2.pdf</a> |
|   |    |  |   |
|   | AP |  | "Atomic Layer Deposition of TiN Films by Alternate Supply of Tetrakis(ethylmethylamino)-Titanium and Ammonia" : Jae-Sik Min, Young-Woong Son, et al.; Jpn. J. Appl. Phys. Vol. 37 (1998) pp. 4999-5004; Part 1, No. 9A; September 1998<br>Japanese Journal of Applied Physics               |
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|  | AA |  |  |                                      |       |                              |                               |    |
|  | AB |  |  |                                      |       |                              |                               |    |
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|  | AH |  |  |                                      |       |                              |                               |    |
|  | AI |  |  |                                      |       |                              |                               |    |
|  | AJ |  |  |                                      |       |                              |                               |    |
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|  |    | Document<br>Number   | Date   | Country                              | Class | Subclas<br>s                 | Translation                   |    |
|  |    |  |  |                                      |       |                              | Yes                           | No |
|  | AK |  |  |                                      |       |                              |                               |    |
|  | AL |  |  |                                      |       |                              |                               |    |
| OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)  |    |  |  |                                      |       |                              |                               |    |
|  | AM |  | "Kinetic modeling of film growth rates of TiN films in atomic layer deposition", Jung-Wook Lim et al., Journal of Applied Physics; Vol. 87, No. 9; 1 May 2000; pp. 4632-4634 |                                      |       |                              |                               |    |
|  |    |  |  |                                      |       |                              |                               |    |
|  | AN |  |  |                                      |       |                              |                               |    |
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|  | AO |  |  |                                      |       |                              |                               |    |
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|  | AP |  |  |                                      |       |                              |                               |    |
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